

FEATURES

Recovers Signal from 100 dB Noise
2 MHz Channel Bandwidth
45 V/ μ s Slew Rate
-120 dB Crosstalk @ 1 kHz
Pin Programmable, Closed-Loop Gains of ± 1 and ± 2
0.05% Closed-Loop Gain Accuracy and Match
100 μ V Channel Offset Voltage (AD630BD)
350 kHz Full Power Bandwidth
Chips Available

PRODUCT DESCRIPTION

The AD630 is a high precision balanced modulator that combines a flexible commutating architecture with the accuracy and temperature stability afforded by laser wafer trimmed thin film resistors. Its signal processing applications include balanced modulation and demodulation, synchronous detection, phase detection, quadrature detection, phase-sensitive detection, lock-in amplification, and square wave multiplication. A network of on-board applications resistors provides precision closed-loop gains of ± 1 and ± 2 with 0.05% accuracy (AD630B). These resistors may also be used to accurately configure multiplexer gains of +1, +2, +3, or +4. Alternatively, external feedback may be employed, allowing the designer to implement high gain or complex switched feedback topologies.

The AD630 can be thought of as a precision op amp with two independent differential input stages and a precision comparator that is used to select the active front end. The rapid response time of this comparator coupled with the high slew rate and fast settling of the linear amplifiers minimize switching distortion. In addition, the AD630 has extremely low crosstalk between channels of -100 dB @ 10 kHz.

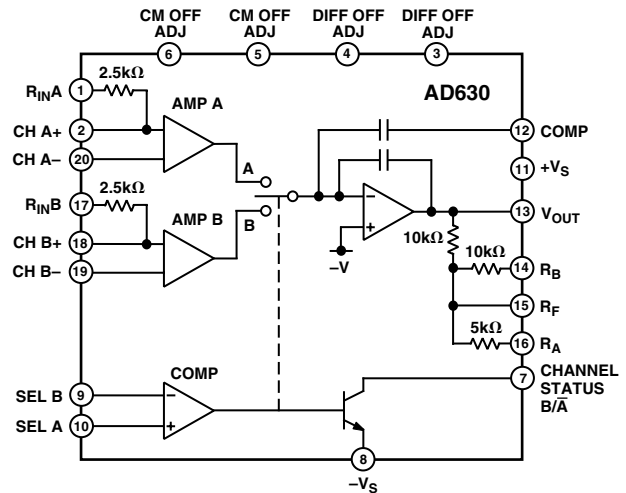
The AD630 is used in precision signal processing and instrumentation applications that require wide dynamic range. When used as a synchronous demodulator in a lock-in amplifier configuration, it can recover a small signal from 100 dB of interfering noise (see Lock-In Amplifier Applications section). Although optimized for operation up to 1 kHz, the circuit is useful at frequencies up to several hundred kilohertz.

Other features of the AD630 include pin programmable frequency compensation, optional input bias current compensation resistors, common-mode and differential-offset voltage adjustment, and a channel status output that indicates which of the two differential inputs is active. This device is now available to Standard Military Drawing (DESC) numbers 5962-8980701RA and 5962-89807012A.

REV. E

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FUNCTIONAL BLOCK DIAGRAM



PRODUCT HIGHLIGHTS

1. The configuration of the AD630 makes it ideal for signal processing applications, such as balanced modulation and demodulation, lock-in amplification, phase detection, and square wave multiplication.
2. The application flexibility of the AD630 makes it the best choice for applications that require precisely fixed gain, switched gain, multiplexing, integrating-switching functions, and high speed precision amplification.
3. The 100 dB dynamic range of the AD630 exceeds that of any hybrid or IC balanced modulator/demodulator and is comparable to that of costly signal processing instruments.
4. The op amp format of the AD630 ensures easy implementation of high gain or complex switched feedback functions. The application resistors facilitate the implementation of most common applications with no additional parts.
5. The AD630 can be used as a 2-channel multiplexer with gains of +1, +2, +3, or +4. The channel separation of 100 dB @ 10 kHz approaches the limit achievable with an empty IC package.
6. The AD630 has pin strappable frequency compensation (no external capacitor required) for stable operation at unity gain without sacrificing dynamic performance at higher gains.
7. Laser trimming of comparator and amplifying channel offsets eliminates the need for external nulling in most cases.

AD630—SPECIFICATIONS (@ 25°C and $\pm V_S = \pm 15$ V, unless otherwise noted.)

Model	AD630J/AD630A			AD630K/AD630B			AD630S			Unit
	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
GAIN										
Open-Loop Gain	90	110		100	120		90	110		dB
$\pm 1, \pm 2$ Closed-Loop Gain Error		0.1				0.05		0.1		%
Closed-Loop Gain Match		0.1				0.05		0.1		%
Closed-Loop Gain Drift		2			2			2		ppm/°C
CHANNEL INPUTS										
V_{IN} Operational Limit ¹	(- $V_S + 4$ V) to ($+V_S - 1$ V)			(- $V_S + 4$ V) to ($+V_S - 1$ V)			(- $V_S + 4$ V) to ($+V_S - 1$ V)			V
Input Offset Voltage			500			100			500	μ V
Input Offset Voltage T_{MIN} to T_{MAX}			800			160			1000	μ V
Input Bias Current		100	300		100	300		100	300	nA
Input Offset Current		10	50		10	50		10	50	nA
Channel Separation @ 10 kHz		100			100			100		dB
COMPARATOR										
V_{IN} Operational Limit ¹	(- $V_S + 3$ V) to ($+V_S - 1.5$ V)			(- $V_S + 3$ V) to ($+V_S - 1.5$ V)			(- $V_S + 3$ V) to ($+V_S - 1.3$ V)			V
Switching Window			± 1.5			± 1.5			± 1.5	mV
Switching Window T_{MIN} to T_{MAX}			± 2.0			± 2.0			± 2.5	mV
Input Bias Current		100	300		100	300		100	300	nA
Response Time (-5 mV to +5 mV Step)		200			200			200		ns
Channel Status I_{SINK} @ $V_{OL} = -V_S + 0.4$ V ²	1.6			1.6			1.6			mA
Pull-Up Voltage			(- $V_S + 33$ V)			(- $V_S + 33$ V)			(- $V_S + 33$ V)	V
DYNAMIC PERFORMANCE										
Unity Gain Bandwidth		2			2			2		MHz
Slew Rate ³		45			45			45		V/ μ s
Settling Time to 0.1% (20 V Step)		3			3			3		μ s
OPERATING CHARACTERISTICS										
Common-Mode Rejection	85	105		90	110		90	110		dB
Power Supply Rejection	90	110		90	110		90	110		dB
Supply Voltage Range	± 5		± 16.5	± 5		± 16.5	± 5		± 16.5	V
Supply Current		4	5		4	5		4	5	mA
OUTPUT VOLTAGE, @ $R_L = 2$ kΩ										
T_{MIN} to T_{MAX}	± 10			± 10			± 10			V
Output Short-Circuit Current		25			25			25		mA
TEMPERATURE RANGES										
Rated Performance—N Package	0		70	0		70		N/A		°C
D Package	-25		+85	-25		+85	-55		+125	°C

NOTES

¹If one terminal of each differential channel or comparator input is kept within these limits the other terminal may be taken to the positive supply.

² I_{SINK} @ $V_{OL} = (-V_S + 1)$; V is typically 4 mA.

³Pin 12 Open. Slew rate with Pin 12 and Pin 13 shorted is typically 35 V/ μ s.

Specifications subject to change without notice.

ABSOLUTE MAXIMUM RATINGS

Supply Voltage	±18 V
Internal Power Dissipation	600 mW
Output Short-Circuit to Ground	Indefinite
Storage Temperature, Ceramic Package	-65°C to +150°C
Storage Temperature, Plastic Package	-55°C to +125°C
Lead Temperature Range (Soldering, 10 sec)	300°C
Maximum Junction Temperature	150°C

THERMAL CHARACTERISTICS

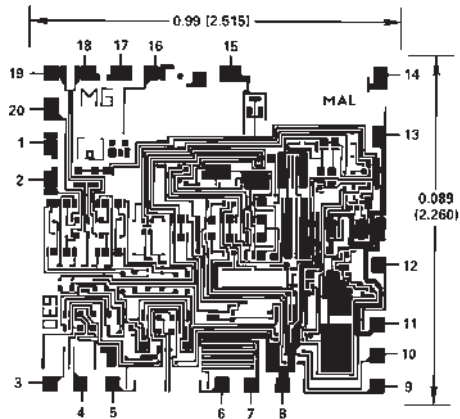
	θ_{JC}	θ_{JA}
20-Lead PDIP (N)	24°C/W	61°C/W
20-Lead Ceramic DIP (D)	35°C/W	120°C/W
20-Lead Leadless Chip Carrier LCC (E)	35°C/W	120°C/W
20-Lead SOIC (R-20)	38°C/W	75°C/W

ORDERING GUIDE

Model	Temperature Ranges	Package Description	Package Option
AD630JN	0°C to 70°C	PDIP	N-20
AD630KN	0°C to 70°C	PDIP	N-20
AD630AR	-25°C to +85°C	SOIC	R-20
AD630AR-REEL	-25°C to +85°C	SOIC 13" Tape and Reel	R-20
AD630AD	-25°C to +85°C	SBDIP	D-20
AD630BD	-25°C to +85°C	SBDIP	D-20
AD630SD	-55°C to +125°C	SBDIP	D-20
AD630SD/883B	-55°C to +125°C	SBDIP	D-20
5962-8980701RA	-55°C to +125°C	SBDIP	D-20
AD630SE/883B	-55°C to +125°C	CLCC	E-20A
5962-89807012A	-55°C to +125°C	CLCC	E-20A
AD630JCHIPS	0°C to 70°C	Chip	
AD630SCHIPS	-55°C to +125°C	Chip	

CHIP METALLIZATION AND PINOUT

Dimensions shown in inches and (millimeters).
Contact factory for latest dimensions.



CHIP AVAILABILITY

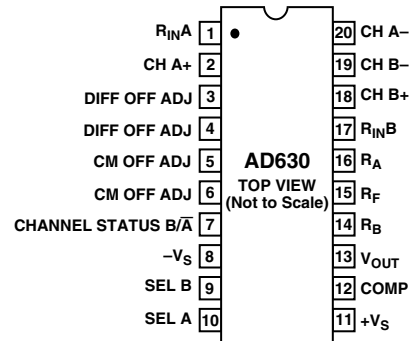
The AD630 is available in laser trimmed, passivated chip form. The figure above shows the AD630 metallization pattern, bonding pads and dimensions. AD630 chips are available; consult factory for details.

CAUTION

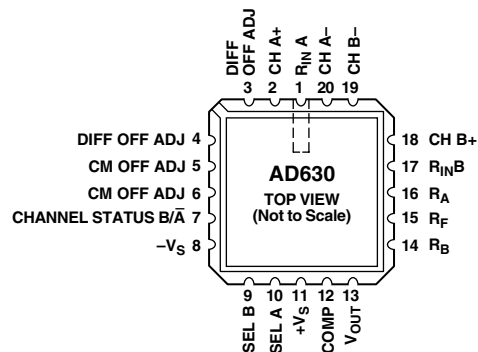
ESD (electrostatic discharge) sensitive device. Electrostatic charges as high as 4000 V readily accumulate on the human body and test equipment and can discharge without detection. Although the AD630 features proprietary ESD protection circuitry, permanent damage may occur on devices subjected to high energy electrostatic discharges. Therefore, proper ESD precautions are recommended to avoid performance degradation or loss of functionality.

PIN CONFIGURATIONS

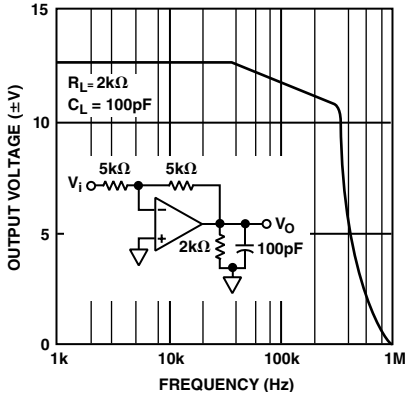
20-Lead SOIC, PDIP, and Cerdip



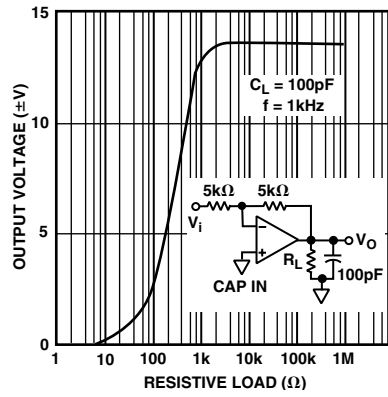
20-Terminal CLCC



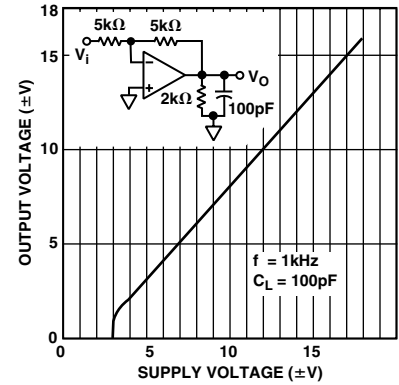
AD630—Typical Performance Characteristics



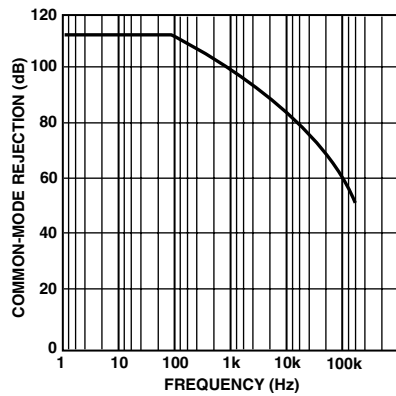
TPC 1. Output Voltage vs. Frequency



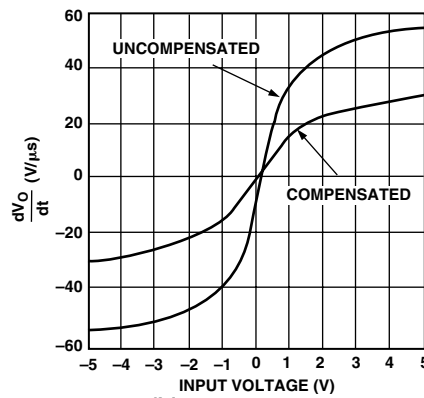
TPC 2. Output Voltage vs. Resistive Load



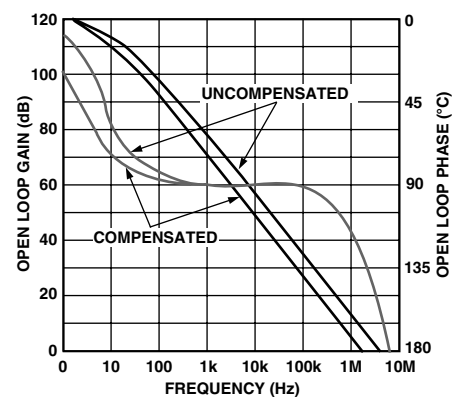
TPC 3. Output Voltage Swing vs. Supply Voltage



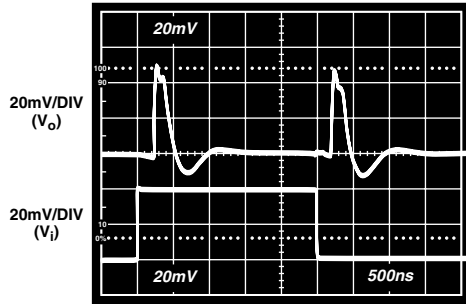
TPC 4. Common-Mode Rejection vs. Frequency



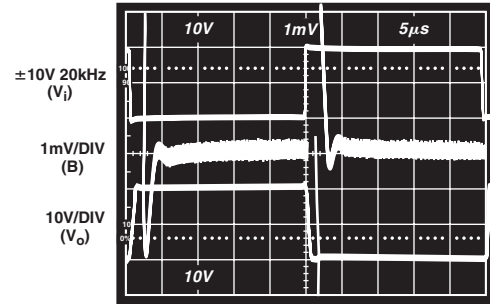
TPC 5. $\frac{dV_O}{dt}$ vs. Input Voltage



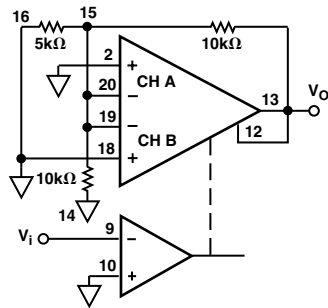
TPC 6. Gain and Phase vs. Frequency



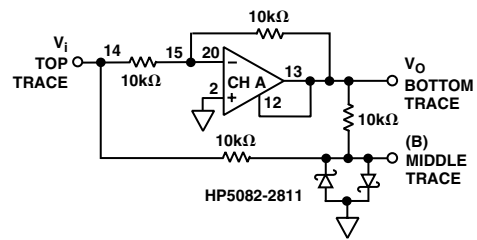
TOP TRACE: V_o
BOTTOM TRACE: V_i



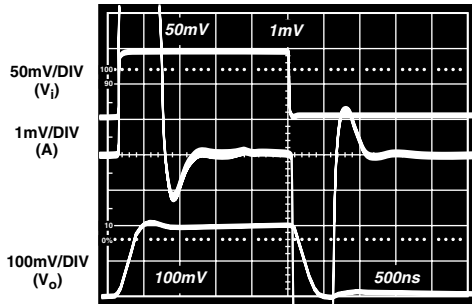
TOP TRACE: V_i
MIDDLE TRACE: SETTLING
ERROR (B)
BOTTOM TRACE: V_o



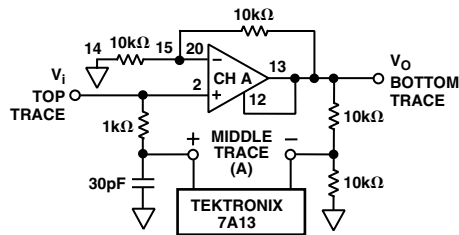
TPC 7. Channel-to-Channel Switch-Settling Characteristic



TPC 9. Large Signal Inverting Step Response



TOP TRACE: V_i
MIDDLE TRACE: SETTLING
ERROR (A)
BOTTOM TRACE: V_o



TPC 8. Small Signal Noninverting Step Response

AD630

the system input tied to 0 V, and a switching or carrier waveform applied to the comparator, a low level square wave will appear at the output. The differential offset adjustment potentiometers can be used to null the amplitude of this square wave (Pins 3 and 4). The common-mode offset adjustment can be used to zero the residual dc output voltage (Pins 5 and 6). These functions should be implemented using 10k trim potentiometers with wipers connected directly to Pin 8 as shown in Figures 9a and 9b.

CHANNEL STATUS OUTPUT

The channel status output, Pin 7, is an open collector output referenced to $-V_S$ that can be used to indicate which of the two input channels is active. The output will be active (pulled low) when Channel A is selected. This output can also be used to supply positive feedback around the comparator. This produces hysteresis which serves to increase noise immunity. Figure 7 shows an example of how hysteresis may be implemented. Note that the feedback signal is applied to the inverting ($-$) terminal of the comparator to achieve positive feedback. This is because the open collector channel status output inverts the output sense of the internal comparator.

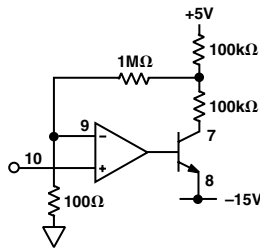


Figure 7. Comparator Hysteresis

The channel status output may be interfaced with TTL inputs as shown in Figure 8. This circuit provides appropriate level shifting from the open-collector AD630 channel status output to TTL inputs.

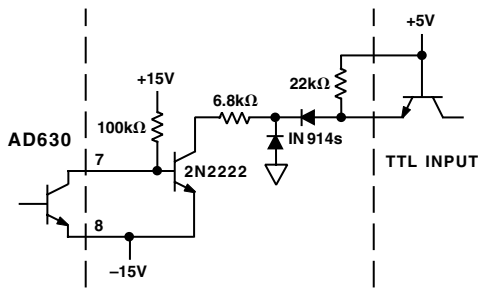


Figure 8. Channel Status—TTL Interface

APPLICATIONS: BALANCED MODULATOR

Perhaps the most commonly used configuration of the AD630 is the balanced modulator. The application resistors provide precise symmetric gains of ± 1 and ± 2 . The ± 1 arrangement is shown in Figure 9a and the ± 2 arrangement is shown in Figure 9b. These cases differ only in the connection of the 10 kΩ feedback resistor (Pin 14) and the compensation capacitor (Pin 12). Note the use of the 2.5 kΩ bias current compensation resistors in these examples. These resistors perform the identical function in the ± 1 gain case. Figure 10 demonstrates the performance of the

AD630 when used to modulate a 100 kHz square wave carrier with a 10 kHz sinusoid. The result is the double sideband suppressed carrier waveform.

These balanced modulator topologies accept two inputs, a signal (or modulation) input applied to the amplifying channels and a reference (or carrier) input applied to the comparator.

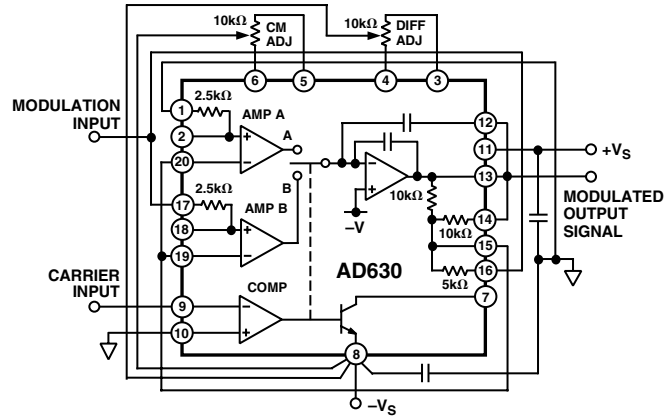


Figure 9a. AD630 Configured as a Gain-of-One Balanced Modulator

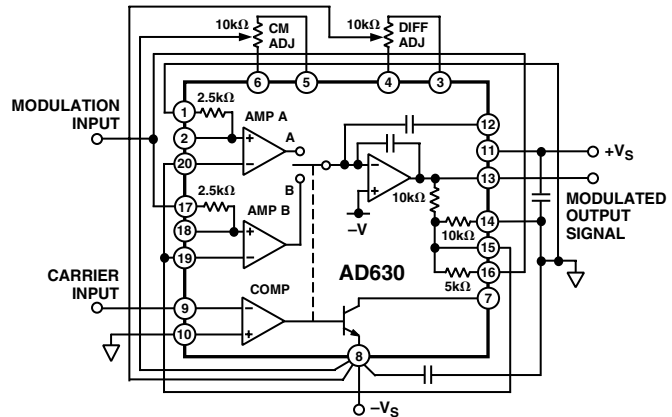


Figure 9b. AD630 Configured as a Gain-of-Two Balanced Modulator

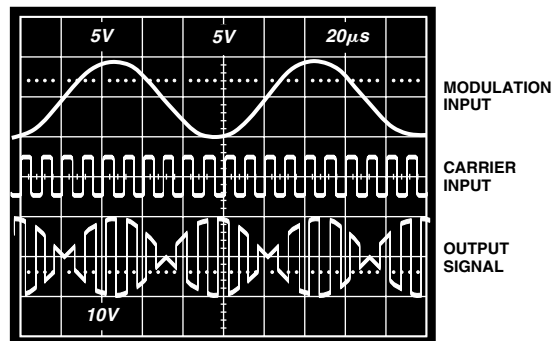


Figure 10. Gain-of-Two Balanced Modulator Sample Waveforms

BALANCED DEMODULATOR

The balanced modulator topology described above will also act as a balanced demodulator if a double sideband suppressed carrier waveform is applied to the signal input and the carrier signal is applied to the reference input. The output under these circumstances will be the baseband modulation signal. Higher order carrier components that can be removed with a low-pass filter will also be present. Other names for this function are synchronous demodulation and phase-sensitive detection.

PRECISION PHASE COMPARATOR

The balanced modulator topologies of Figures 9a and 9b can also be used as precision phase comparators. In this case, an ac waveform of a particular frequency is applied to the signal input and a waveform of the same frequency is applied to the reference input. The dc level of the output (obtained by low-pass filtering) will be proportional to the signal amplitude and phase difference between the input signals. If the signal amplitude is held constant, the output can be used as a direct indication of the phase. When these input signals are 90° out of phase, they are said to be in quadrature and the AD630 dc output will be zero.

PRECISION RECTIFIER ABSOLUTE VALUE

If the input signal is used as its own reference in the balanced modulator topologies, the AD630 will act as a precision rectifier. The high frequency performance will be superior to that which can be achieved with diode feedback and op amps. There are no diode drops that the op amp must “leap over” with the commutating amplifier.

LVDT SIGNAL CONDITIONER

Many transducers function by modulating an ac carrier. A linear variable differential transformer (LVDT) is a transducer of this type. The amplitude of the output signal corresponds to core displacement. Figure 11 shows an accurate synchronous demodulation system which can be used to produce a dc voltage that corresponds to the LVDT core position. The inherent precision and temperature stability of the AD630 reduce demodulator drift to a second-order effect.

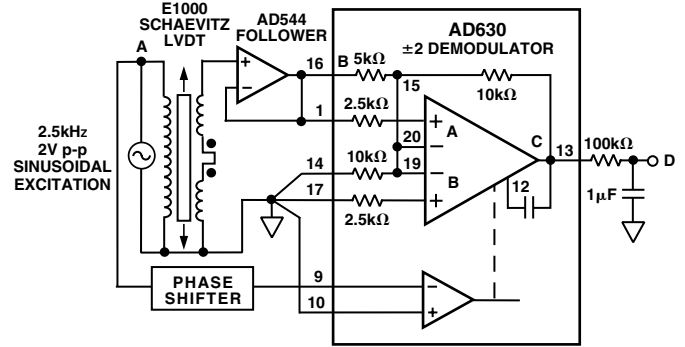


Figure 11. LVDT Signal Conditioner

AC BRIDGE

Bridge circuits that use dc excitation are often plagued by errors caused by thermocouple effects, 1/f noise, dc drifts in the electronics, and line noise pick-up. One way to get around these problems is to excite the bridge with an ac waveform, amplify the bridge output with an ac amplifier, and synchronously demodulate the resulting signal. The ac phase and amplitude information from the bridge is recovered as a dc signal at the output of the synchronous demodulator. The low frequency system noise, dc drifts, and demodulator noise all get mixed to the carrier frequency and can be removed by means of a low-pass filter. Dynamic response of the bridge must be traded off against the amount of attenuation required to adequately suppress these residual carrier components in the selection of the filter.

Figure 12 is an example of an ac bridge system with the AD630 used as a synchronous demodulator. The bridge is excited by a 1 V 400 Hz excitation. Trace A in Figure 13 is the amplified bridge signal. Trace B is the output of the synchronous demodulator and Trace C is the filtered dc system output.

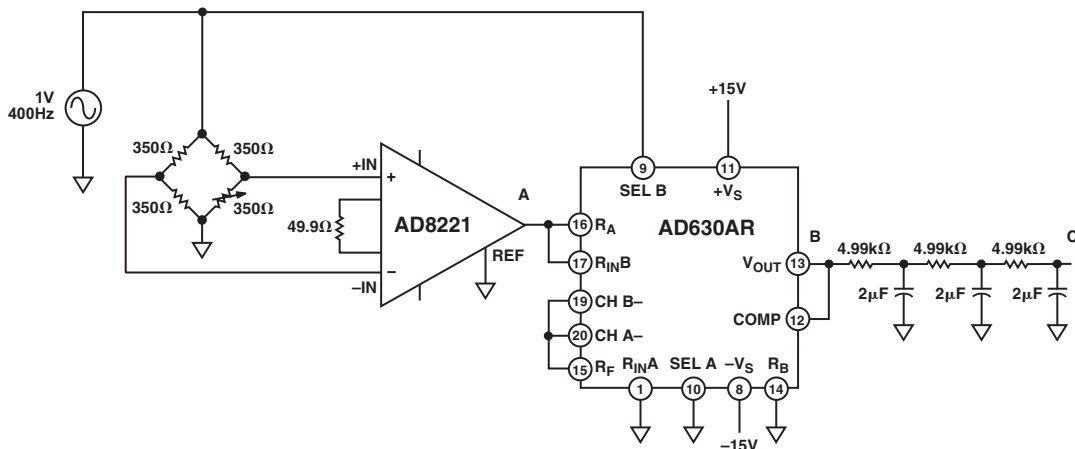


Figure 12. AC Bridge System

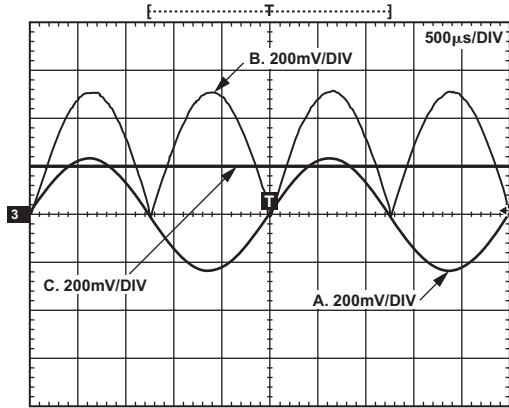


Figure 13. AC Bridge Waveforms (1 V Excitation)

LOCK-IN AMPLIFIER APPLICATIONS

Lock-in amplification is a technique used to separate a small, narrow-band signal from interfering noise. The lock-in amplifier acts as a detector and narrow-band filter combined. Very small signals can be detected in the presence of large amounts of uncorrelated noise when the frequency and phase of the desired signal are known.

The lock-in amplifier is basically a synchronous demodulator followed by a low-pass filter. An important measure of performance in a lock-in amplifier is the dynamic range of its demodulator. The schematic diagram of a demonstration circuit which exhibits the dynamic range of an AD630 as it might be used in a lock-in amplifier is shown in Figure 14. Figure 15 is an oscilloscope photo demonstrating the large dynamic range of the AD630. The photo shows the recovery of a signal modulated at 400 Hz from a noise signal approximately 100,000 times larger.

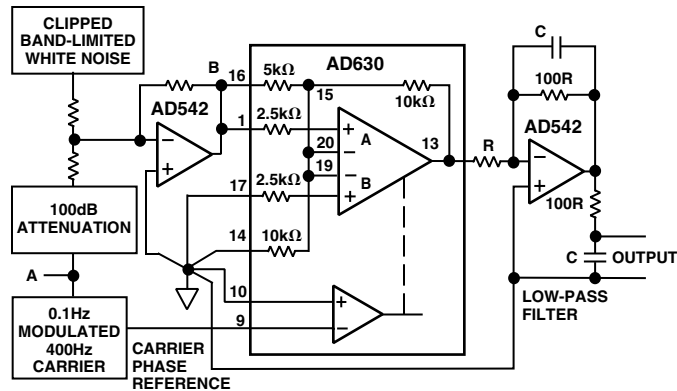


Figure 14. Lock-In Amplifier

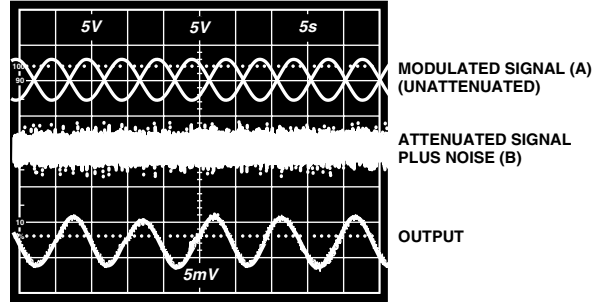


Figure 15. Lock-In Amplifier Waveforms

The test signal is produced by modulating a 400 Hz carrier with a 0.1 Hz sine wave. The signals produced, for example, by chopped radiation (i.e., IR, optical) detectors may have similar low frequency components. A sinusoidal modulation is used for clarity of illustration. This signal is produced by a circuit similar to Figure 9b and is shown in the upper trace of Figure 15. It is attenuated 100,000 times normalized to the output, B, of the summing amplifier. A noise signal that might represent, for example, background and detector noise in the chopped radiation case, is added to the modulated signal by the summing amplifier. This signal is simply band limited clipped white noise. Figure 15 shows the sum of attenuated signal plus noise in the center trace. This combined signal is demodulated synchronously using phase information derived from the modulator, and the result is low-pass filtered using a 2-pole simple filter which also provides a gain of 100 to the output. This recovered signal is the lower trace of Figure 15.

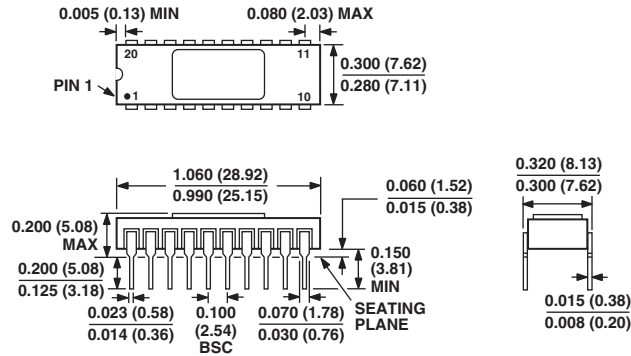
The combined modulated signal and interfering noise used for this illustration is similar to the signals often requiring a lock-in amplifier for detection. The precision input performance of the AD630 provides more than 100 dB of signal range and its dynamic response permits it to be used with carrier frequencies more than two orders of magnitude higher than in this example. A more sophisticated low-pass output filter will aid in rejecting wider bandwidth interference.

OUTLINE DIMENSIONS

20-Lead Side-Brazed Ceramic Dual In-Line Package [SBDIP]

(D-20)

Dimensions shown in inches and (millimeters)

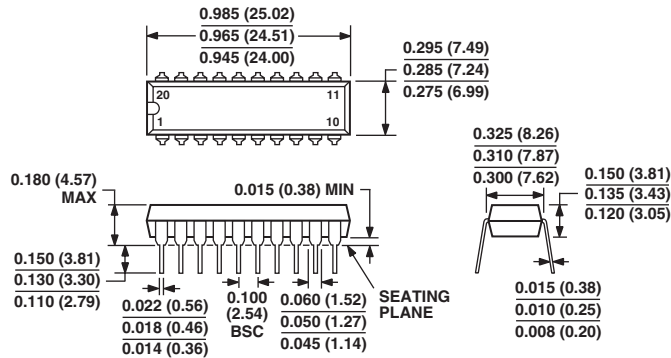


CONTROLLING DIMENSIONS ARE IN INCHES; MILLIMETER DIMENSIONS (IN PARENTHESES) ARE ROUNDED-OFF INCH EQUIVALENTS FOR REFERENCE ONLY AND ARE NOT APPROPRIATE FOR USE IN DESIGN

20-Lead Plastic Dual In-Line Package [PDIP]

(N-20)

Dimensions shown in inches and (millimeters)

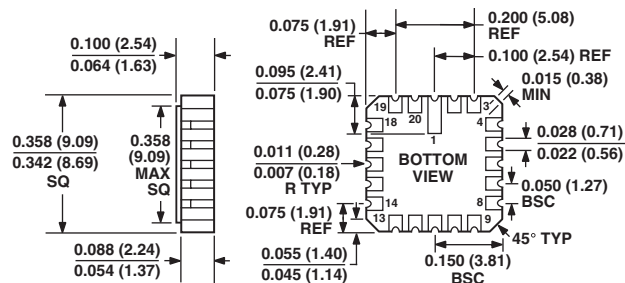


COMPLIANT TO JEDEC STANDARDS MO-095-AE
CONTROLLING DIMENSIONS ARE IN INCHES; MILLIMETER DIMENSIONS (IN PARENTHESES) ARE ROUNDED-OFF INCH EQUIVALENTS FOR REFERENCE ONLY AND ARE NOT APPROPRIATE FOR USE IN DESIGN

20-Terminal Ceramic Leadless Chip Carrier [LCC]

(E-20A)

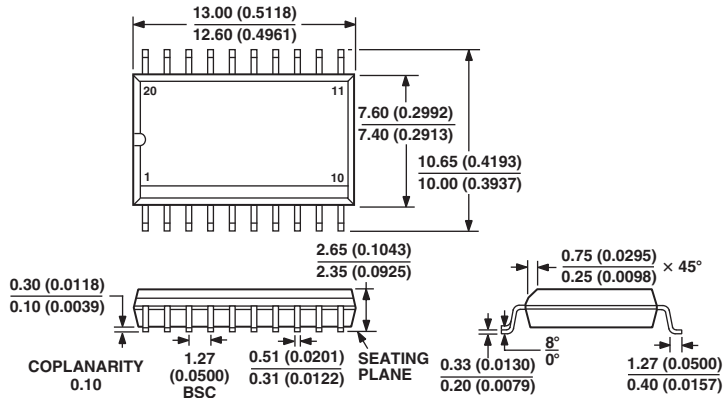
Dimensions shown in inches and (millimeters)



CONTROLLING DIMENSIONS ARE IN INCHES; MILLIMETERS DIMENSIONS (IN PARENTHESES) ARE ROUNDED-OFF INCH EQUIVALENTS FOR REFERENCE ONLY AND ARE NOT APPROPRIATE FOR USE IN DESIGN

20-Lead Standard Small Outline Package [SOIC] Wide Body (R-20)

Dimensions shown in millimeters and (inches)



COMPLIANT TO JEDEC STANDARDS MS-013AC
CONTROLLING DIMENSIONS ARE IN MILLIMETERS; INCH DIMENSIONS
(IN PARENTHESES) ARE ROUNDED-OFF MILLIMETER EQUIVALENTS FOR
REFERENCE ONLY AND ARE NOT APPROPRIATE FOR USE IN DESIGN

Revision History

Location	Page
6/04—Data Sheet changed from REV. D to REV. E.	
Changes to ORDERING GUIDE	3
Replaced Figure 12	9
Changes to AC BRIDGE section	9
Replaced Figure 13	10
Changes to LOCK-IN AMPLIFIER APPLICATIONS	10
Updated OUTLINE DIMENSIONS	11
6/01—Data Sheet changed from REV. C to REV. D.	
Changes to SPECIFICATION TABLE	2
Changes to THERMAL CHARACTERISTICS	3
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Changes to PIN CONFIGURATIONS	3
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